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Mira et al.

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(54) **U-SHAPED CONDENSER HEAT SINK FOR LOW PROFILE MODULES**

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(73) Assignee: **Heatscape, Inc.**, Morgan Hill, CA (US)

(**) Term: **14 Years**

(21) Appl. No.: **29/473,920**

(22) Filed: **Nov. 26, 2013**

(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/179**

(58) **Field of Classification Search**
USPC D13/179; 165/80.3, 104.26, 104.33, 165/122, 151, 185; 257/706, 707, 718–722; 361/695, 697, 700, 702, 704, 709, 710, 361/711, 719
See application file for complete search history.

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(74) *Attorney, Agent, or Firm* — Kilpatrick Townsend & Stockton LLP

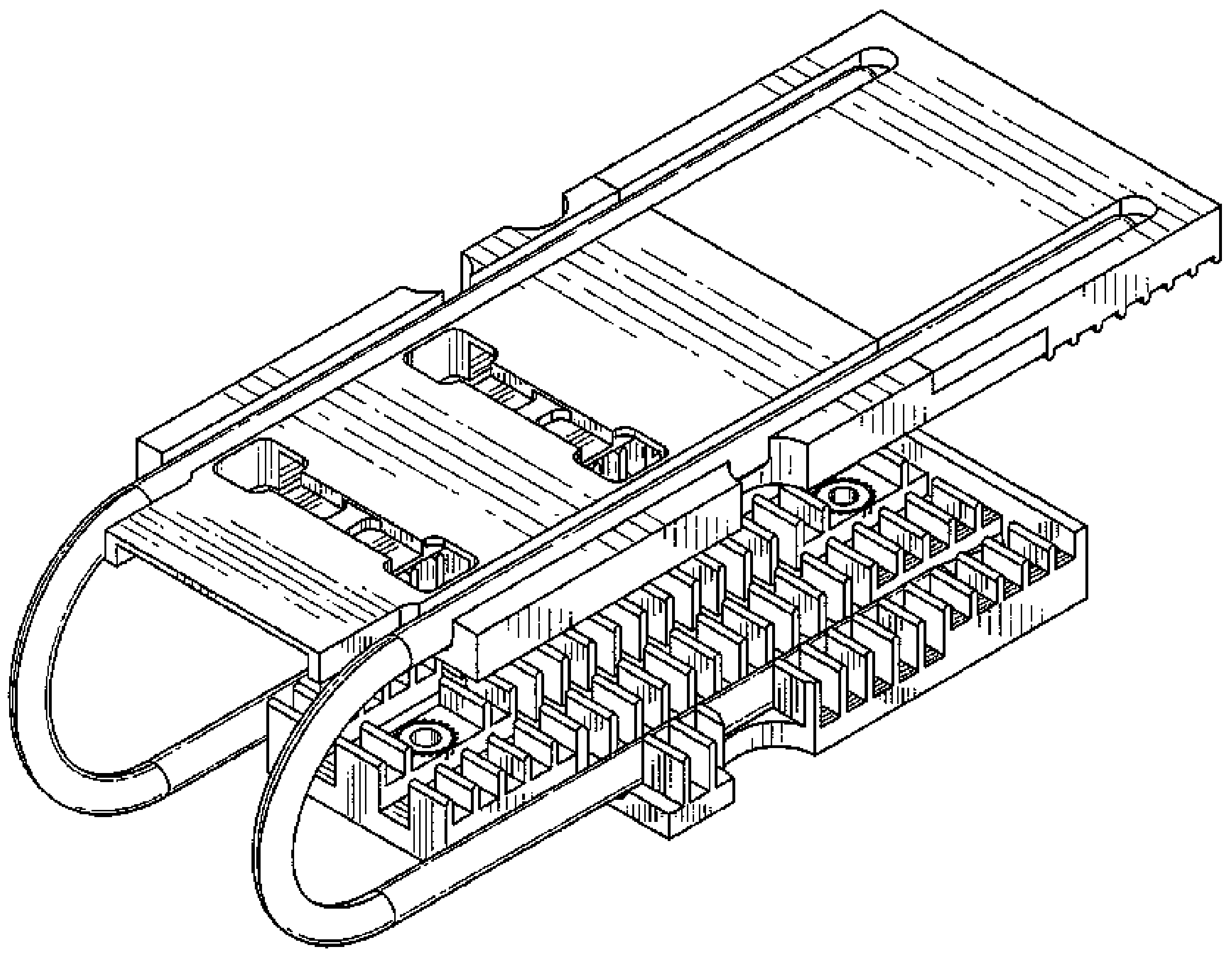
(57) CLAIM

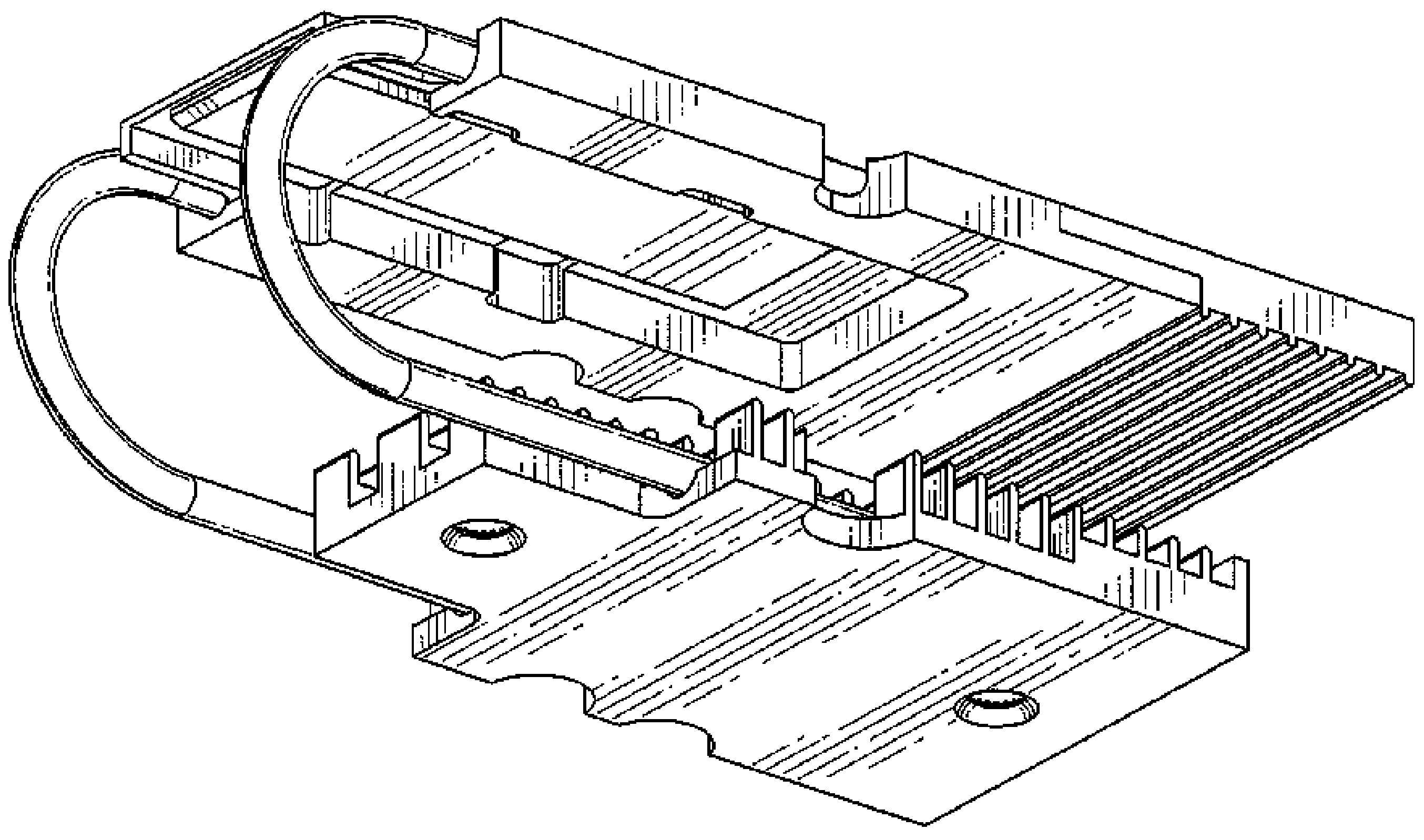
The ornamental design for a U-shaped condenser heat sink for low profile modules, as shown and described.

DESCRIPTION

FIG. **1** is a top perspective view of a U-shaped condenser heat sink for low profile modules showing our new design;
FIG. **2** is a bottom perspective view thereof;
FIG. **3** is a front elevational view thereof;
FIG. **4** is a rear elevational view thereof;
FIG. **5** is a top plan view thereof;
FIG. **6** is a bottom plan view thereof;
FIG. **7** is a left side elevational view thereof;
FIG. **8** is a right side elevational view thereof;
FIG. **9** is a top perspective view of one U-shaped condenser heat sink for low profile modules connected with a generic circuit board, another near and unconnected from a generic circuit board and showing two modules that are to be received by each of the U-shaped condenser heat sink for low profile modules; and,
FIG. **10** shows the assembly of FIG. **9** when assembled for integration, showing one module fully received and another module partially received by the U-shaped condenser heat sink for low profile modules.
The generic circuit boards and the modules shown FIGS. **9-10** form no part of the claimed design.
The broken line showing on the drawing disclosure is for illustrative purposes only and forms no part of the claimed design.

1 Claim, 9 Drawing Sheets





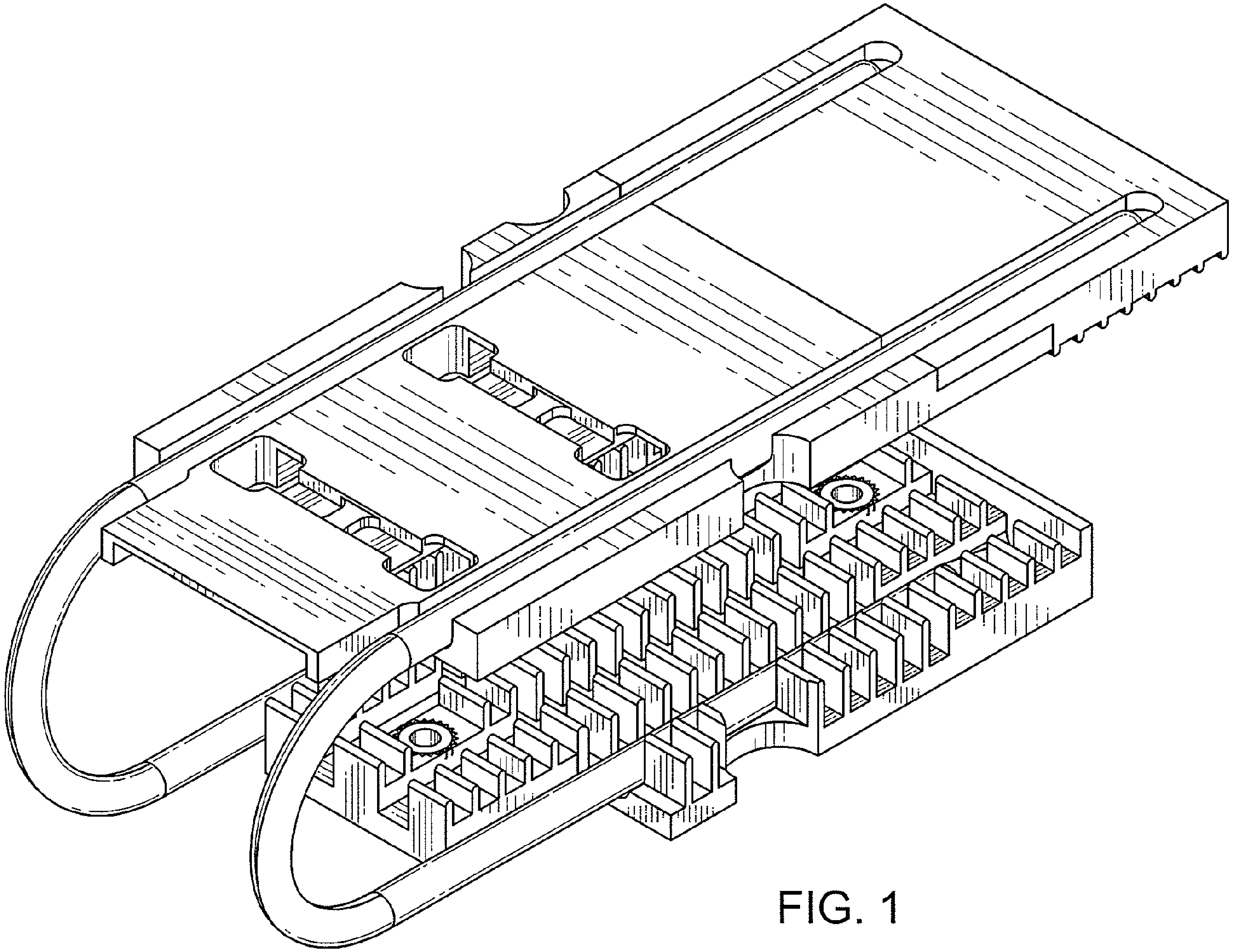


FIG. 1

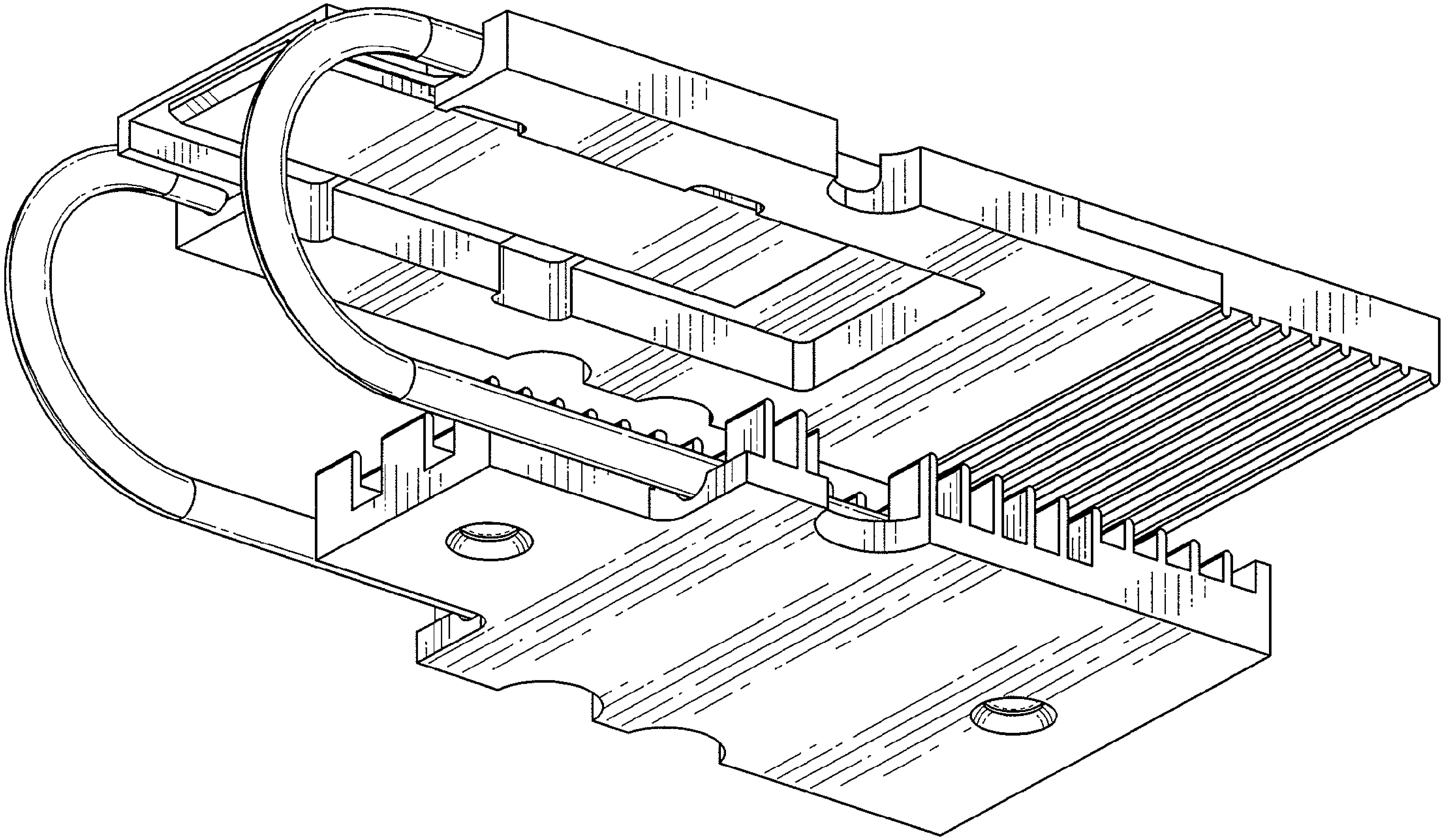


FIG. 2

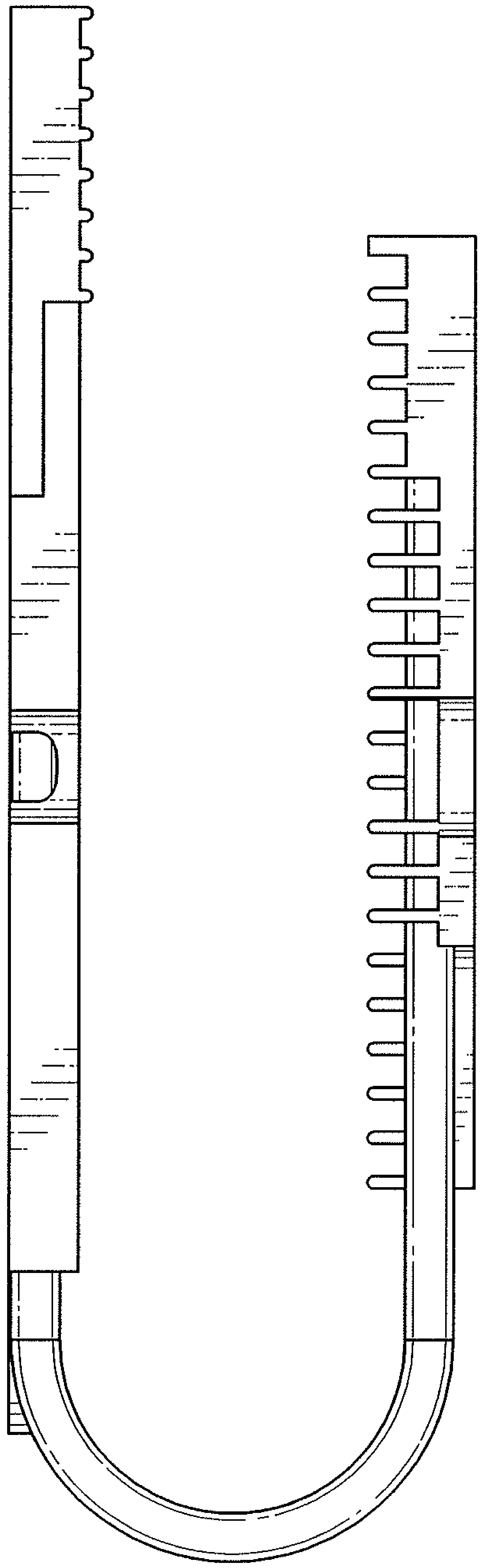


FIG. 3

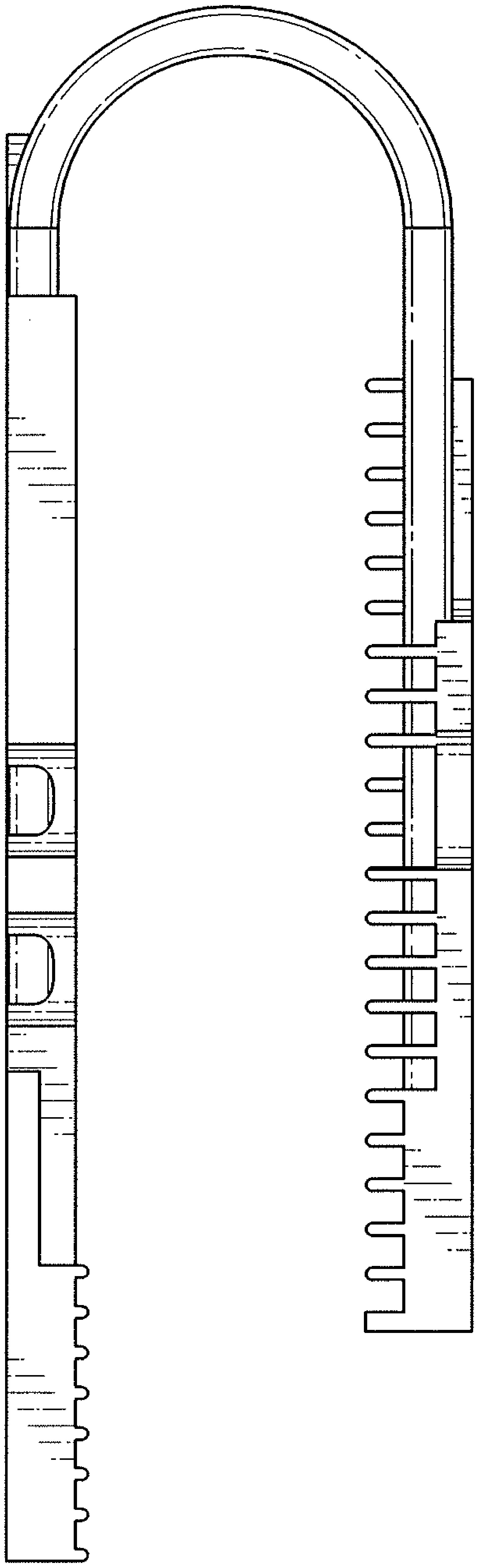


FIG. 4

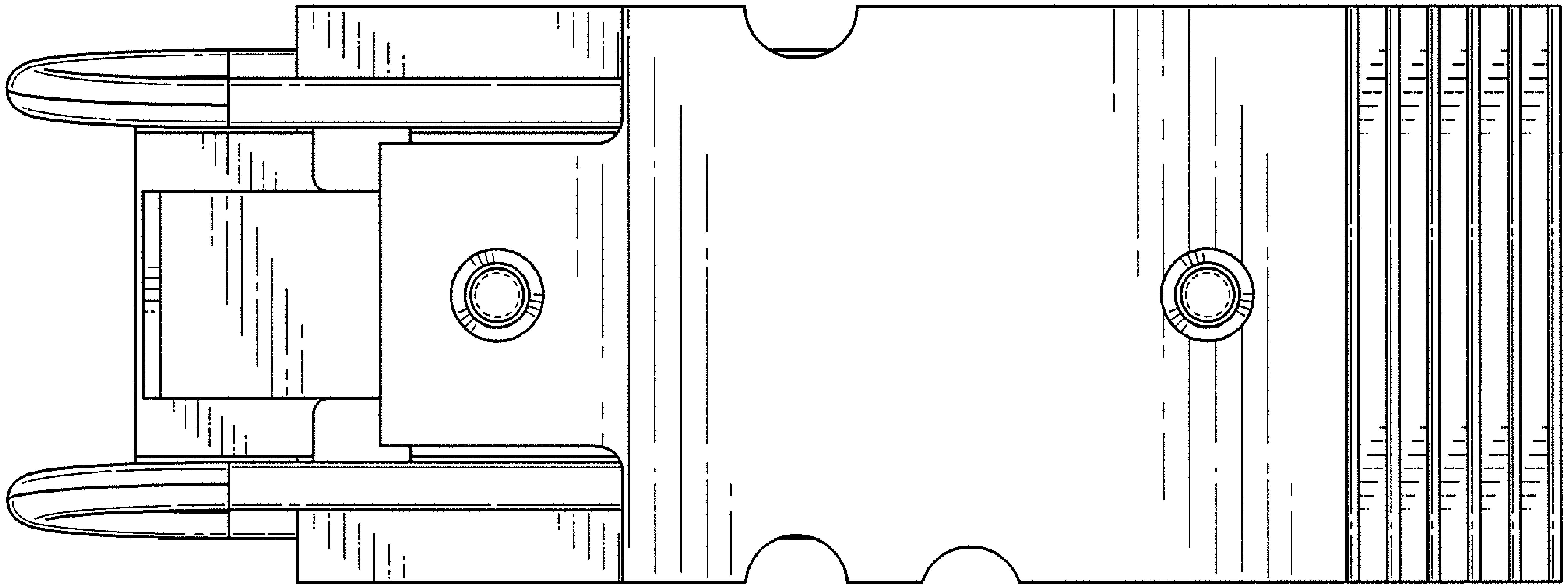


FIG. 5

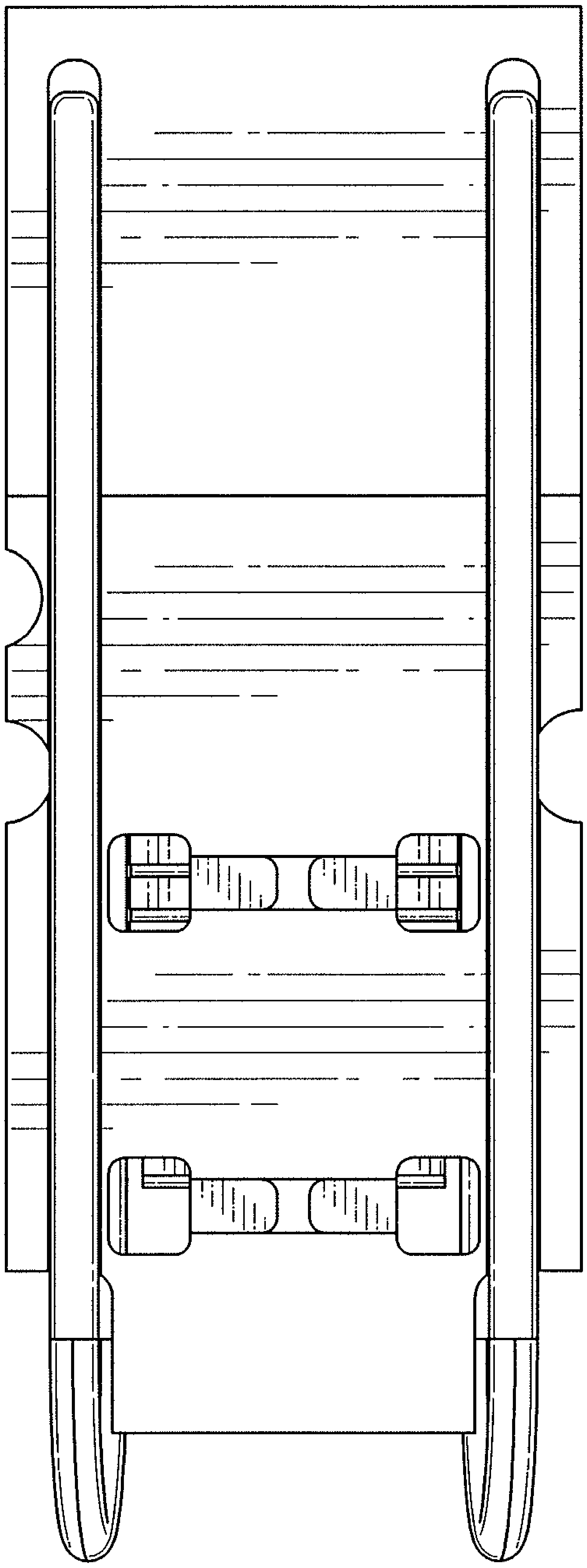


FIG. 6

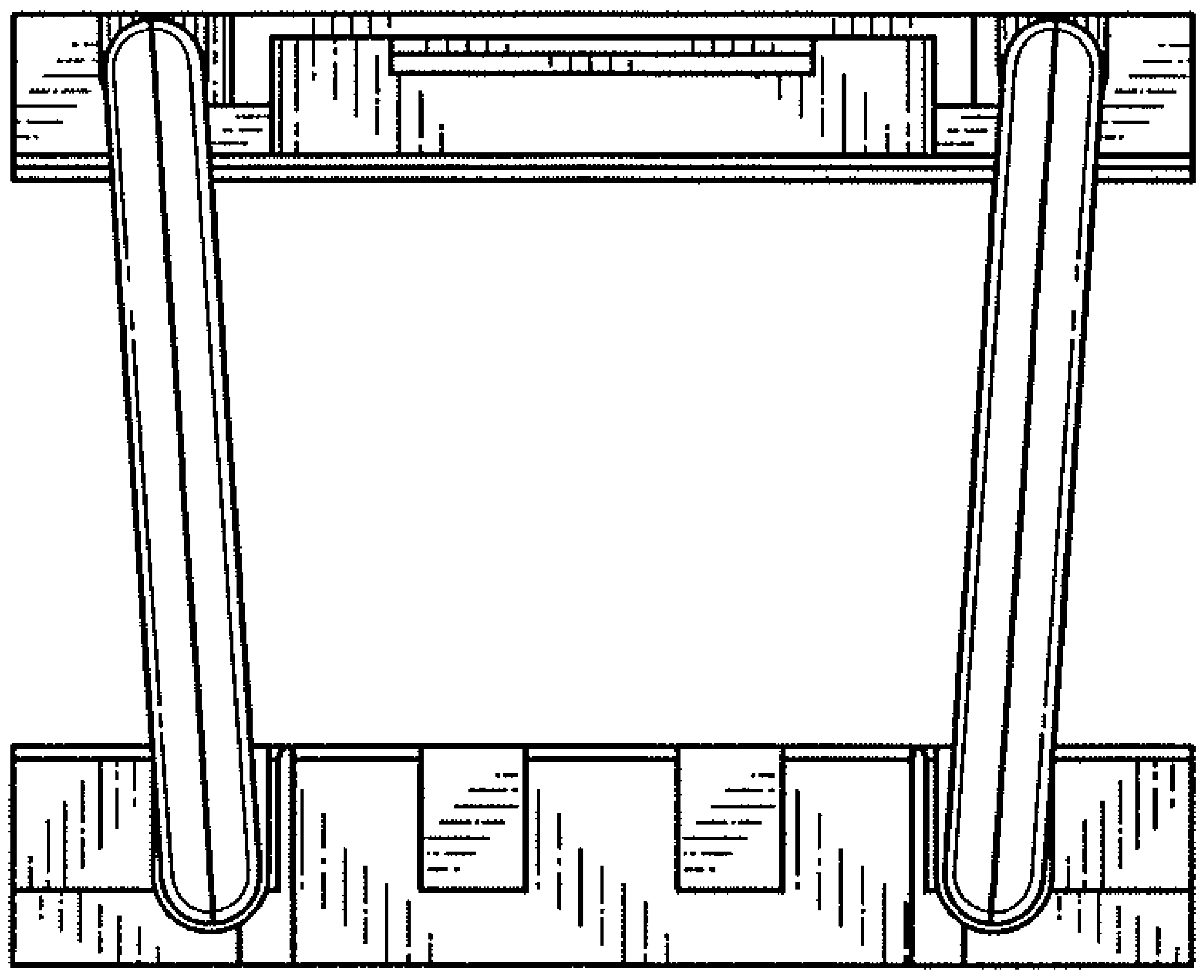


FIG. 7

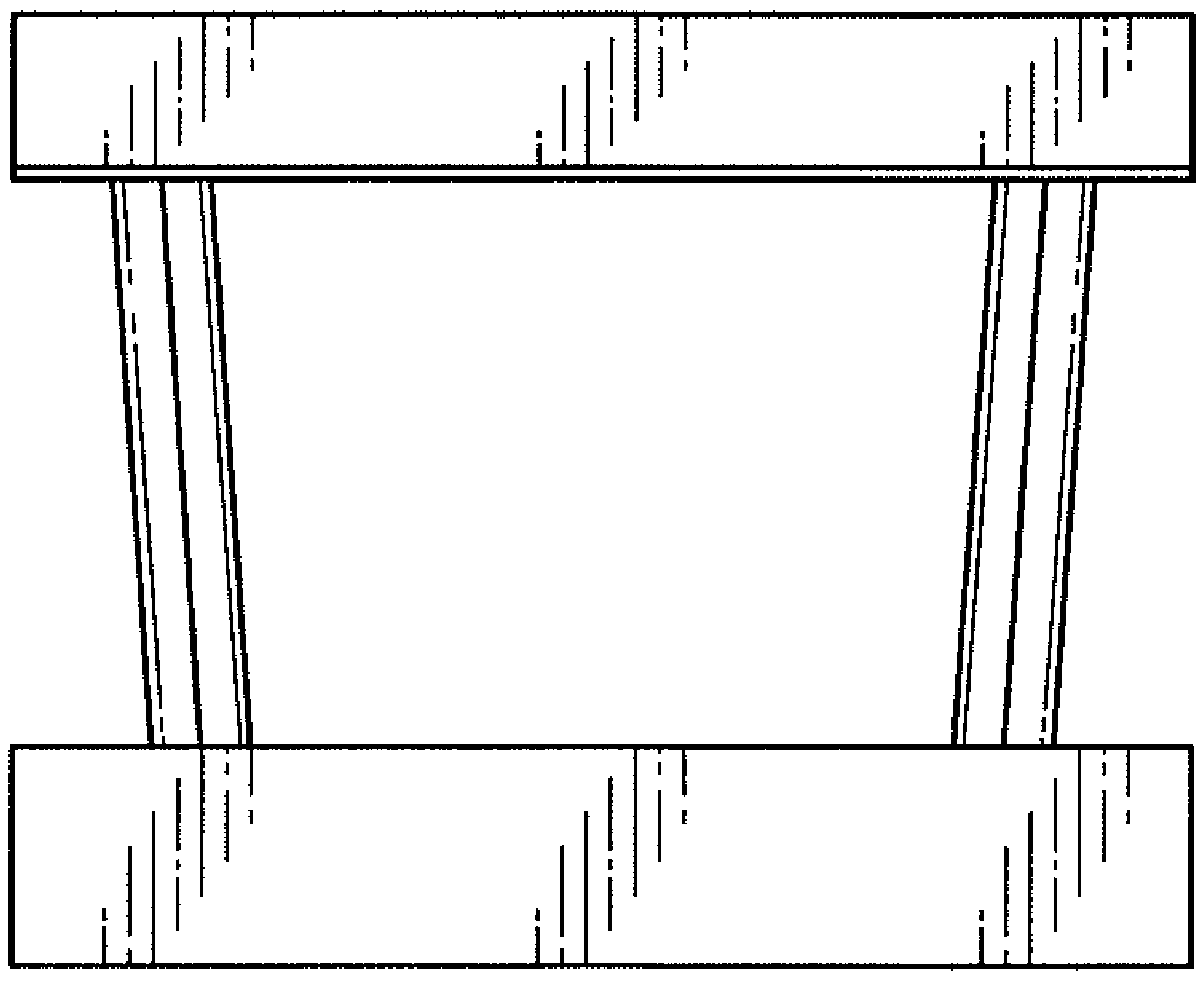


FIG. 8

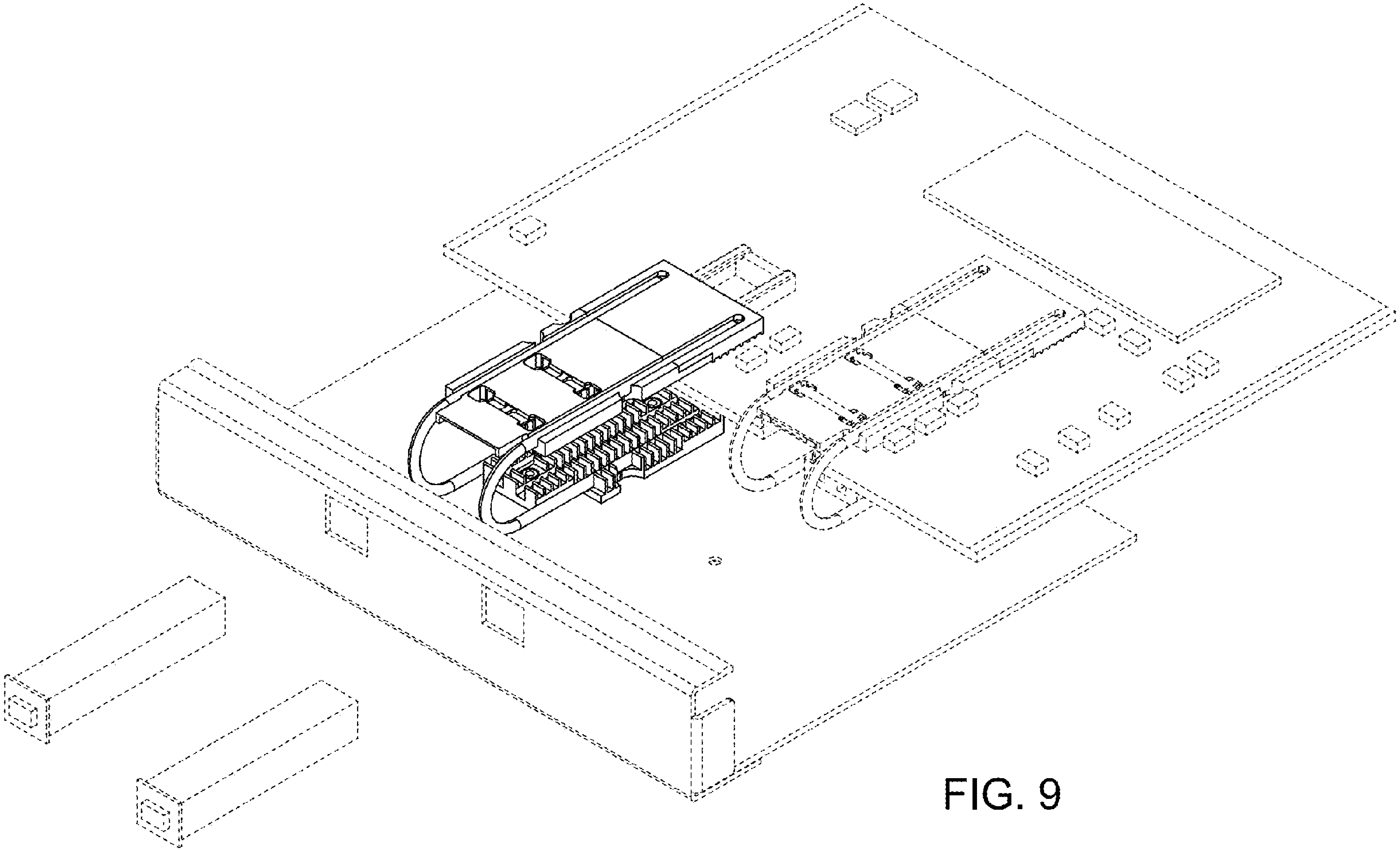


FIG. 9

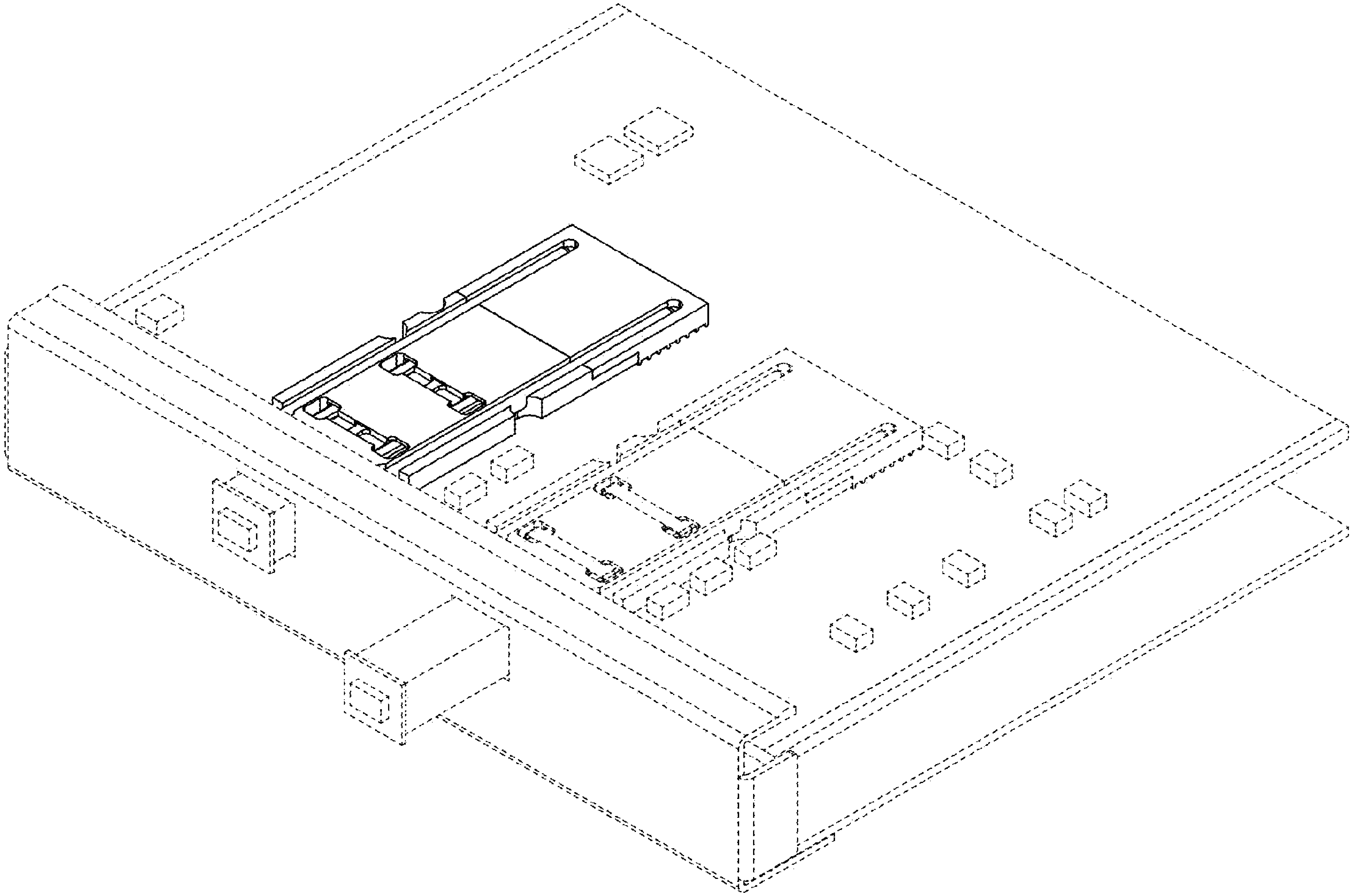


FIG. 10